Driver Transistor

PNP Silicon

Features

- Moisture Sensitivity Level: 1
- ESD Rating:
 - Human Body Model 4 kV
 - Machine Model 400 V
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V _{CEO}	-80	Vdc
Collector-Base Voltage	V _{CBO}	-80	Vdc
Emitter-Base Voltage	V _{EBO}	-4.0	Vdc
Collector Current – Continuous	Ι _C	-500	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board $T_A = 25^{\circ}C$	PD	150	mW
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	833	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



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SC-70 (SOT-323) CASE 419 STYLE 3



MARKING DIAGRAM





M = Date Code* = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBTA56WT1G	SC–70 (Pb–Free)	3,000 / Tape & Reel
SMMBTA56WT1G	SC–70 (Pb–Free)	3,000 / Tape & Reel
SMMBTA56WT3G	SC-70 (Pb-Free)	10,000 / Tape & Reel

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}Date Code orientation may vary depending upon manufacturing location.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector – Emitter Breakdown Voltage (Note 1) $(I_C = -1.0 \text{ mAdc}, I_B = 0)$	V _{(BR)CEO}	-80	-	Vdc
Emitter-Base Breakdown Voltage ($I_E = -100 \ \mu Adc, I_C = 0$)	V _{(BR)EBO}	-4.0	_	Vdc
Collector Cutoff Current (V _{CE} = -60 Vdc, I _B = 0)	ICES	_	-0.1	μAdc
Collector Cutoff Current $(V_{CB} = -60 \text{ Vdc}, I_E = 0)$ $(V_{CB} = -80 \text{ Vdc}, I_E = 0)$	Ісво	- -		μAdc
ON CHARACTERISTICS				
DC Current Gain (I _C = -10 mAdc, V _{CE} = -1.0 Vdc) (I _C = -100 mAdc, V _{CE} = -1.0 Vdc)	h _{FE}	100 100		-
Collector – Emitter Saturation Voltage ($I_C = -100$ mAdc, $I_B = -10$ mAdc)	V _{CE(sat)}	_	-0.25	Vdc
Base – Emitter On Voltage (I _C = –100 mAdc, V _{CE} = –1.0 Vdc)	V _{BE(on)}	_	-1.2	Vdc
SMALL-SIGNAL CHARACTERISTICS			1	1

 \mathbf{f}_{T}

50

_

MHz

Current-Gain – Bandwidth Product (Note 2) (I_C = -100 mAdc, V_{CE} = -1.0 Vdc, f = 100 MHz)

1. Pulse Test: Pulse Width \leq 300 µs, Duty Cycle \leq 2.0%. 2. f_T is defined as the frequency at which |h_{fe}| extrapolates to unity.



*Total Shunt Capacitance of Test Jig and Connectors For PNP Test Circuits, Reverse All Voltage Polarities

Figure 1. Switching Time Test Circuits





Figure 4. Switching Time

Figure 5. Active-Region Safe Operating Area





Figure 8. Collector Saturation Region

Figure 9. Base–Emitter Temperature Coefficient

PACKAGE DIMENSIONS

SC-70 (SOT-323) CASE 419-04 ISSUE N



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.70 REF			0.028 REF		
b	0.30	0.35	0.40	0.012	0.014	0.016
с	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.10	2.20	0.071	0.083	0.087
Е	1.15	1.24	1.35	0.045	0.049	0.053
е	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC			0.026 BSC		
L	0.20	0.38	0.56	0.008	0.015	0.022
HE	2.00	2.10	2.40	0.079	0.083	0.095



SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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